



# BC52xPAS-Q series

60 V, 1 A PNP medium power transistors

Rev. 1 — 24 October 2024

Product data sheet

## 1. General description

PNP medium power transistor series encapsulated in an ultra thin DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package with medium power capability and visible and solderable side pads.

## 2. Features and benefits

- High collector current capability  $I_C$  and  $I_{CM}$
- Reduced Printed-Circuit Board (PCB) area requirements
- Exposed heat sink for excellent thermal and electrical conductivity
- Two current gain selections
- Leadless very small SMD plastic package with medium power capability
- Suitable for Automatic Optical Inspection (AOI) of solder joint
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- Linear voltage regulators
- Battery driven devices
- MOSFET drivers
- High-side switches
- Power management
- Amplifiers

## 4. Quick reference data

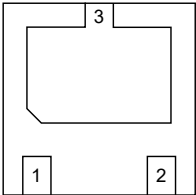
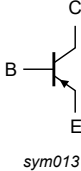
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base		-	-	-60	V
$I_C$	collector current			-	-	-1	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms		-	-	-2	A
$h_{FE}$	DC current gain						
	BC52PAS-Q	$V_{CE} = -2$ V; $I_C = -150$ mA; $T_{amb} = 25$ °C	[1]	63	-	250	
	BC52-10PAS-Q		[1]	63	-	160	
	BC52-16PAS-Q		[1]	100	-	250	

[1] pulsed;  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p>Transparent top view DFN2020D-3 (SOT1061D)</p>	 <p>sym013</p>
2	E	emitter		
3	C	collector		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">BC52PAS-Q</a>	DFN2020D-3	plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); no leads; 3 terminals; 1.3 mm pitch; 2 mm x 2 mm x 0.65 mm body	<a href="#">SOT1061D</a>
<a href="#">BC52-10PAS-Q</a>			
<a href="#">BC52-16PAS-Q</a>			

7. Marking

Table 4. Marking codes

Type number	Marking code
BC52PAS-Q	C7
BC52-10PAS-Q	C8
BC52-16PAS-Q	C9

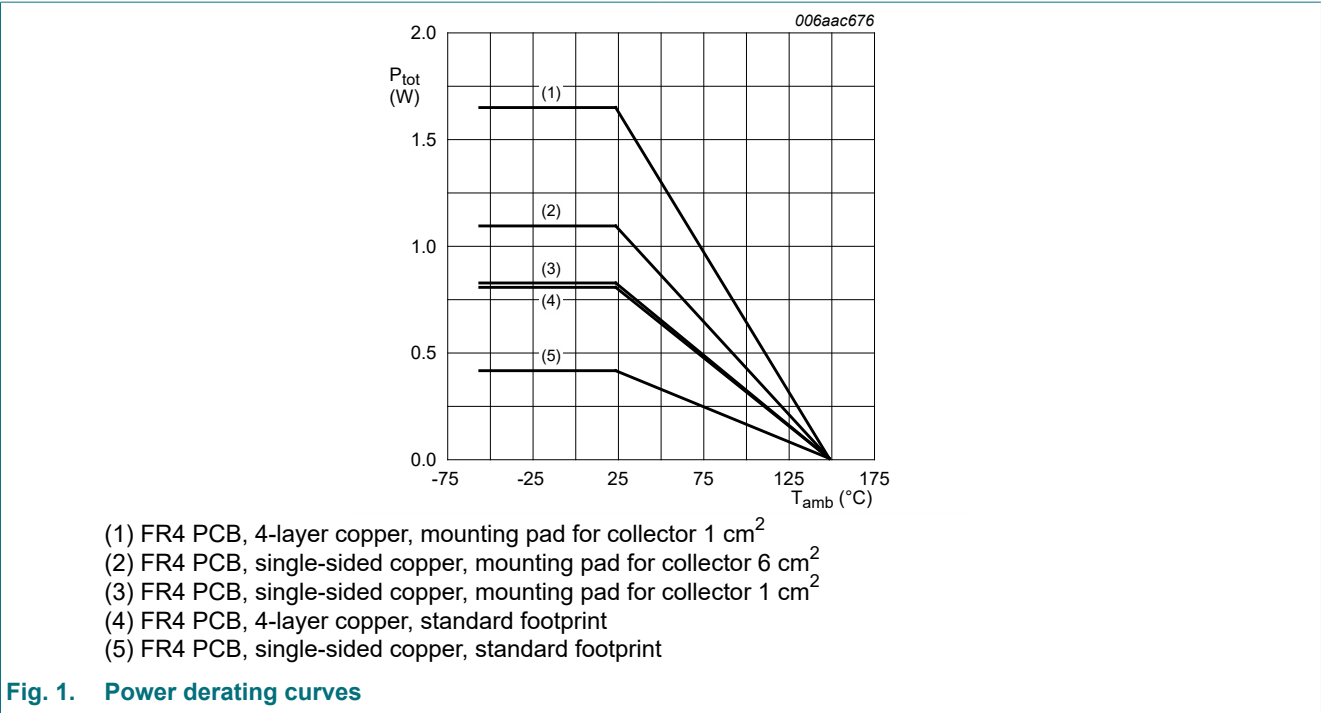
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter		-	-60	V
V <sub>CEO</sub>	collector-emitter voltage	open base		-	-60	V
V <sub>EBO</sub>	emitter-base voltage	open collector		-	-5	V
I <sub>C</sub>	collector current			-	-1	A
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms		-	-2	A
I <sub>B</sub>	base current			-	-0.3	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.42	W
			[2]	-	0.81	W
			[3]	-	0.83	W
			[4]	-	1.1	W
			[5]	-	1.65	W
T <sub>j</sub>	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.
- [5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	298	K/W
			[2]	-	-	154	K/W
			[3]	-	-	151	K/W
			[4]	-	-	114	K/W
			[5]	-	-	76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	20	K/W

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.  
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.  
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.  
[5] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.

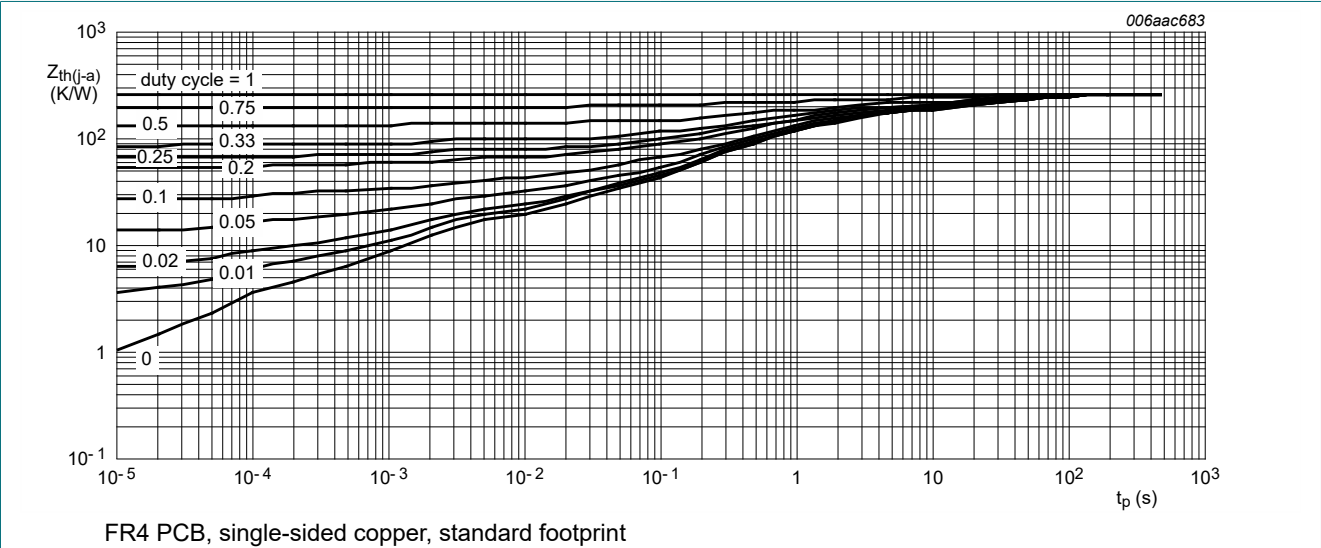


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

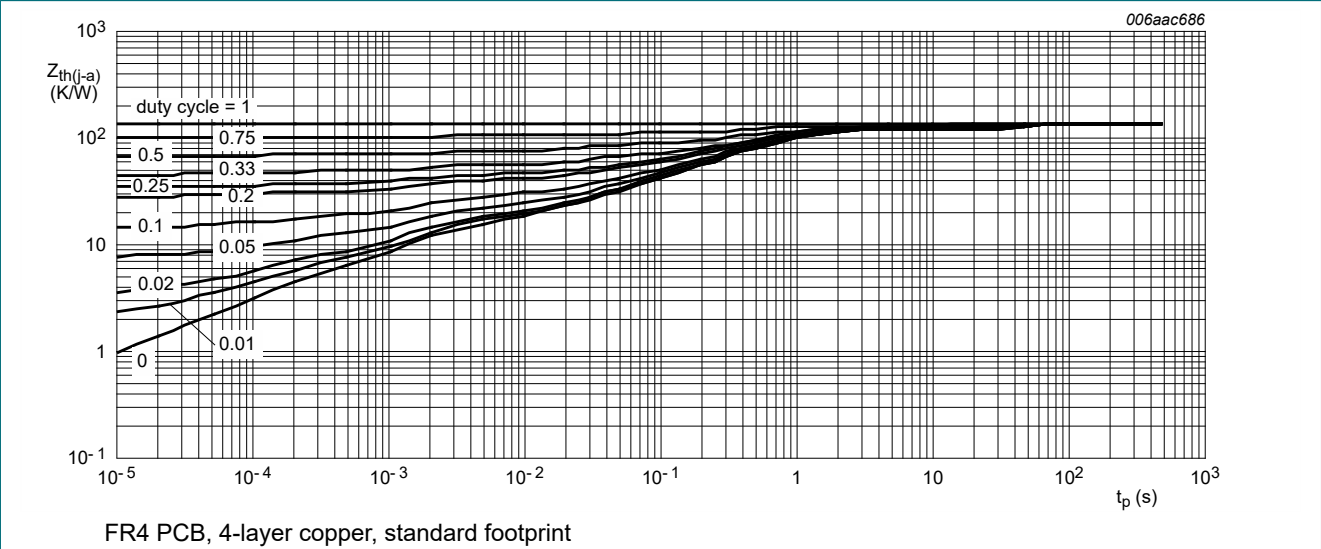
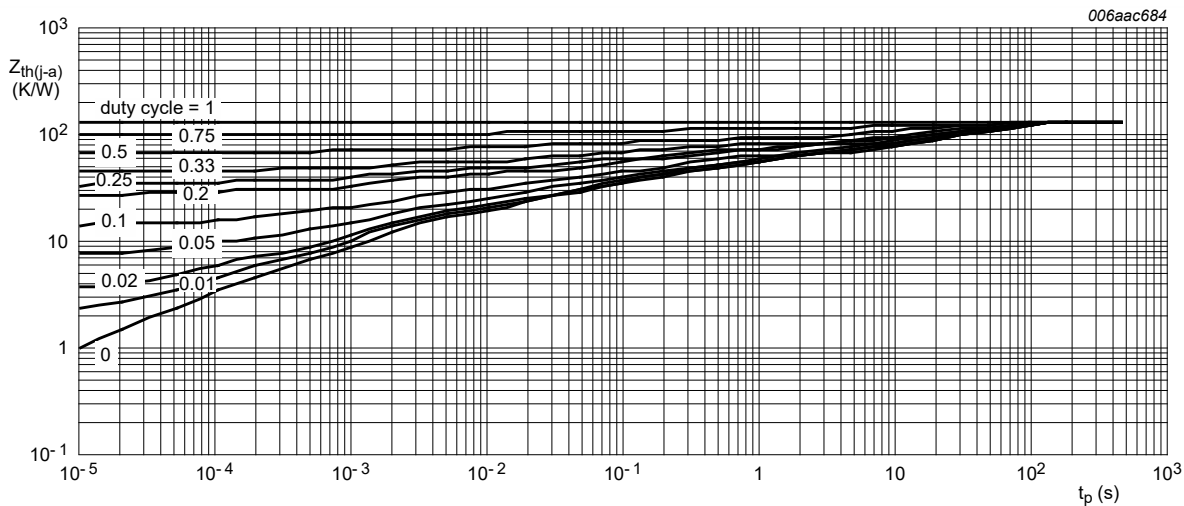
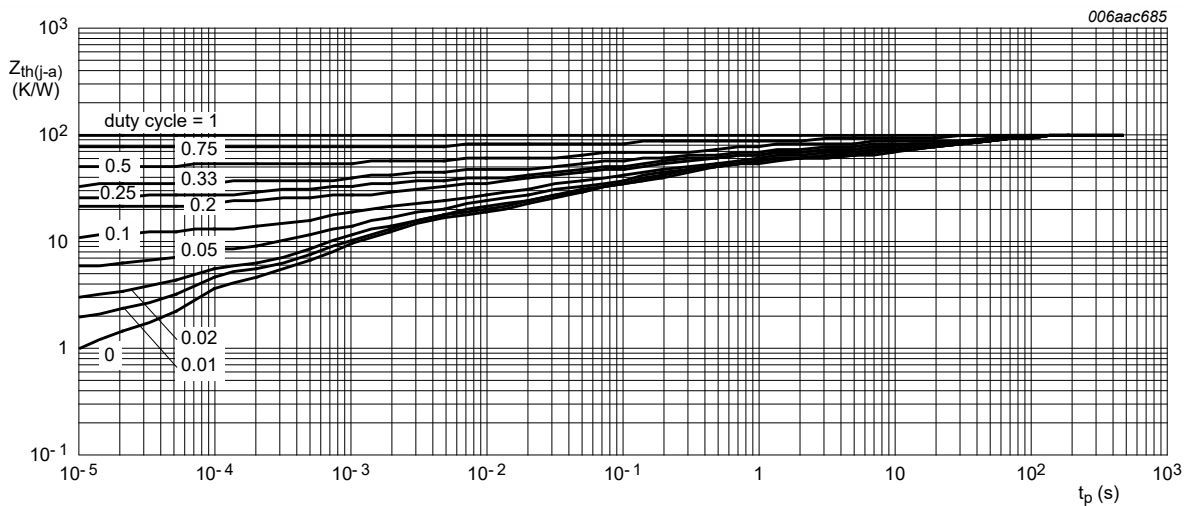


Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



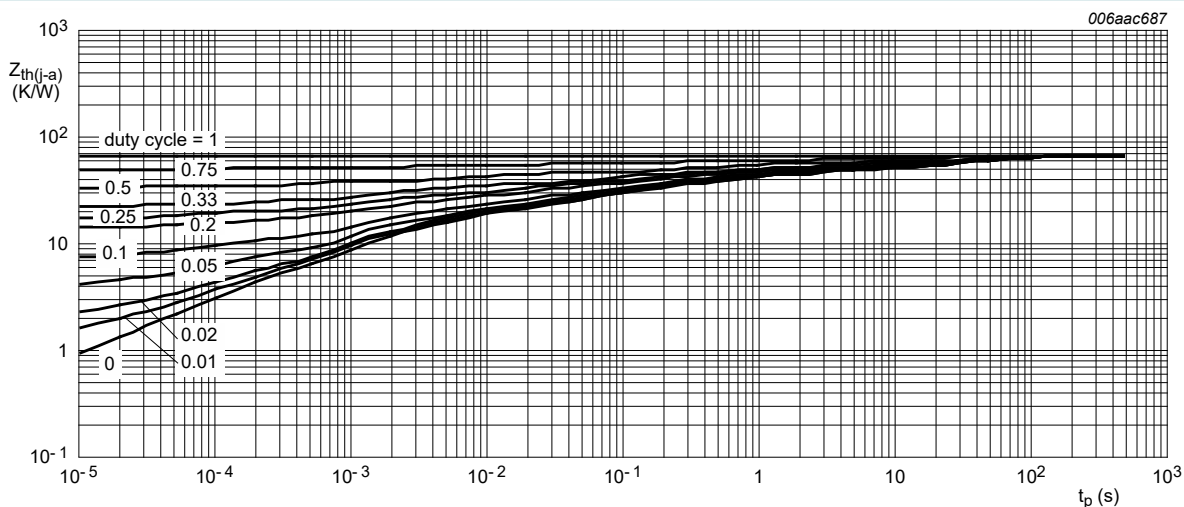
FR4 PCB, single-sided copper, mounting pad for collector 1 cm<sup>2</sup>

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, single-sided copper, mounting pad for collector 6 cm<sup>2</sup>

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, 4-layer copper, mounting pad for collector 1 cm<sup>2</sup>

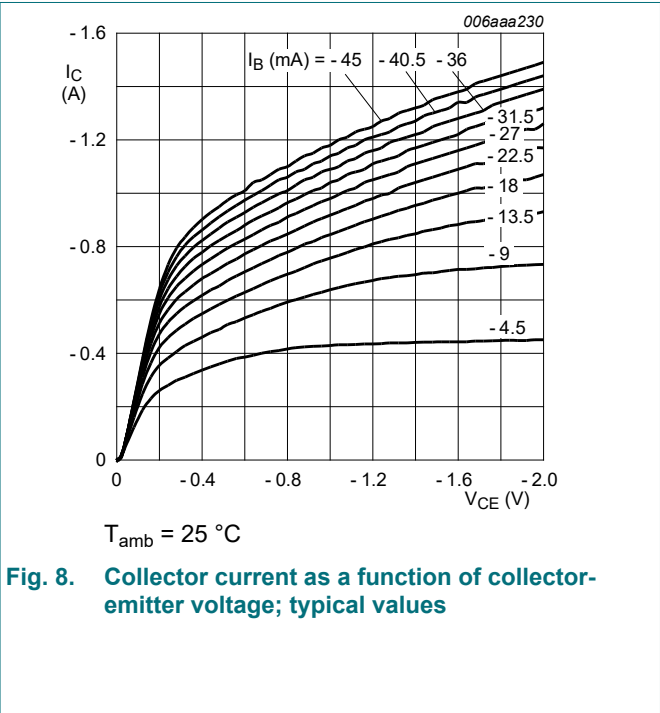
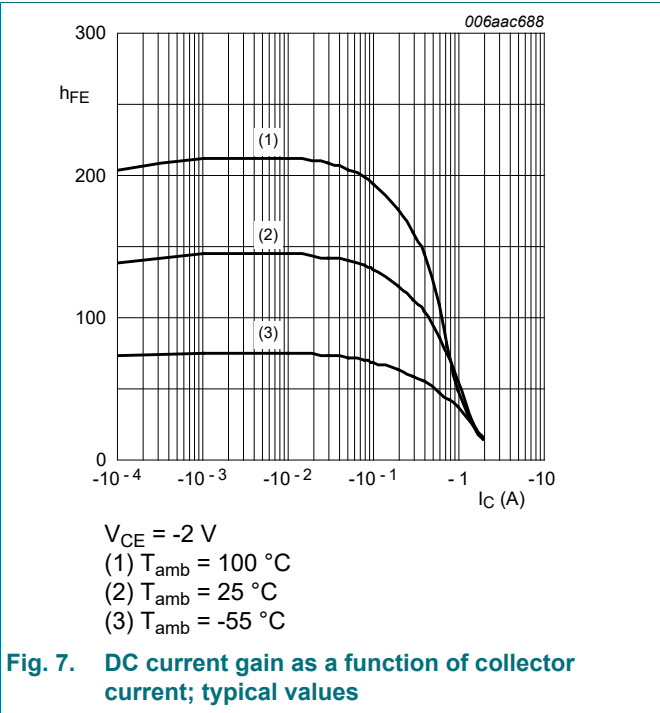
Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current (emitter open)	$V_{CB} = -30\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_{amb} = 25\text{ °C}$		-	-	-100	nA
		$V_{CB} = -30\text{ V}$ ; $I_E = 0\text{ A}$ ; $T_{amb} = 150\text{ °C}$		-	-	-10	μA
$I_{EBO}$	emitter-base cut-off current (collector open)	$V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$ ; $T_{amb} = 25\text{ °C}$		-	-	-100	nA
$h_{FE}$	DC current gain						
	BC52PAS-Q	$V_{CE} = -2\text{ V}$ ; $I_C = -5\text{ mA}$ ; $T_{amb} = 25\text{ °C}$		63	-	-	
	BC52-10PAS-Q			63	-	-	
	BC52-16PAS-Q			63	-	-	
	BC52PAS-Q	$V_{CE} = -2\text{ V}$ ; $I_C = -150\text{ mA}$ ; $T_{amb} = 25\text{ °C}$	[1]	63	-	250	
	BC52-10PAS-Q		[1]	63	-	160	
	BC52-16PAS-Q		[1]	100	-	250	
	BC52PAS-Q	$V_{CE} = -2\text{ V}$ ; $I_C = -500\text{ mA}$ ; $T_{amb} = 25\text{ °C}$	[1]	40	-	-	
	BC52-10PAS-Q		[1]	40	-	-	
	BC52-16PAS-Q		[1]	40	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -500\text{ mA}$ ; $I_B = -50\text{ mA}$ ; $T_{amb} = 25\text{ °C}$	[1]	-	-	-500	mV
$V_{BE}$	base-emitter voltage	$V_{CE} = -2\text{ V}$ ; $I_C = -500\text{ mA}$ ; $T_{amb} = 25\text{ °C}$	[1]	-	-	-1	V
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}$ ; $i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$ ; $T_{amb} = 25\text{ °C}$		-	15	-	pF
$f_T$	transition frequency	$V_{CE} = -5\text{ V}$ ; $I_C = -50\text{ mA}$ ; $f = 100\text{ MHz}$ ; $T_{amb} = 25\text{ °C}$		-	145	-	MHz

[1] pulsed;  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$



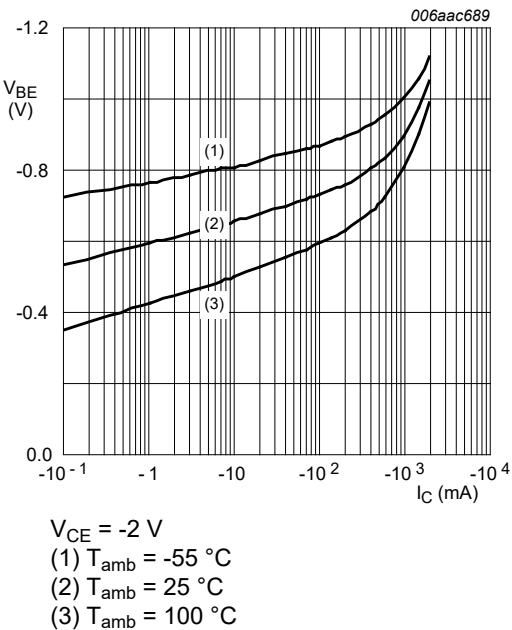


Fig. 9. Base-emitter voltage as a function of collector current; typical values

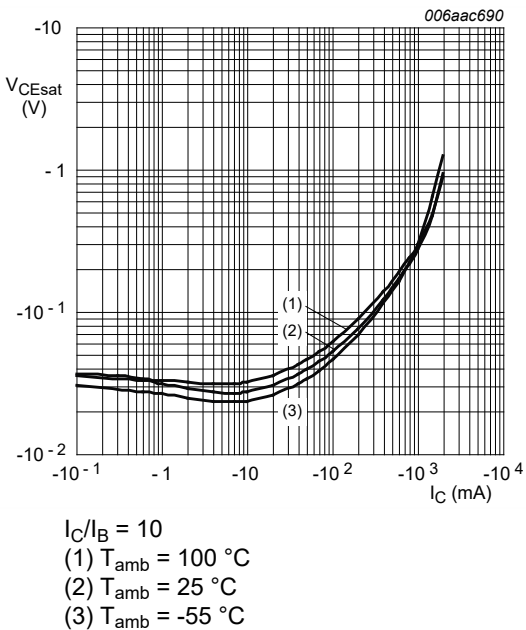


Fig. 10. Collector-emitter saturation voltage as a function of collector current; typical values

11. Test information

11.1. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

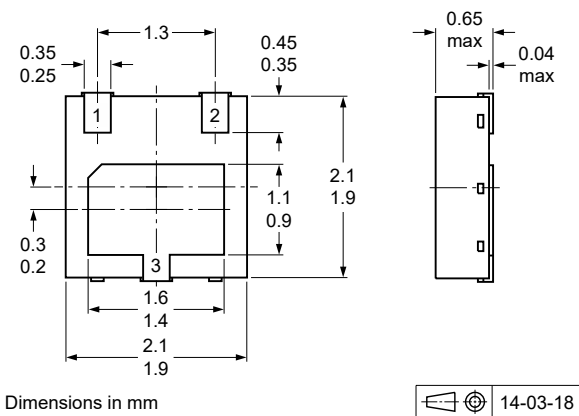


Fig. 11. Package outline DFN2020D-3 (SOT1061D)

13. Soldering

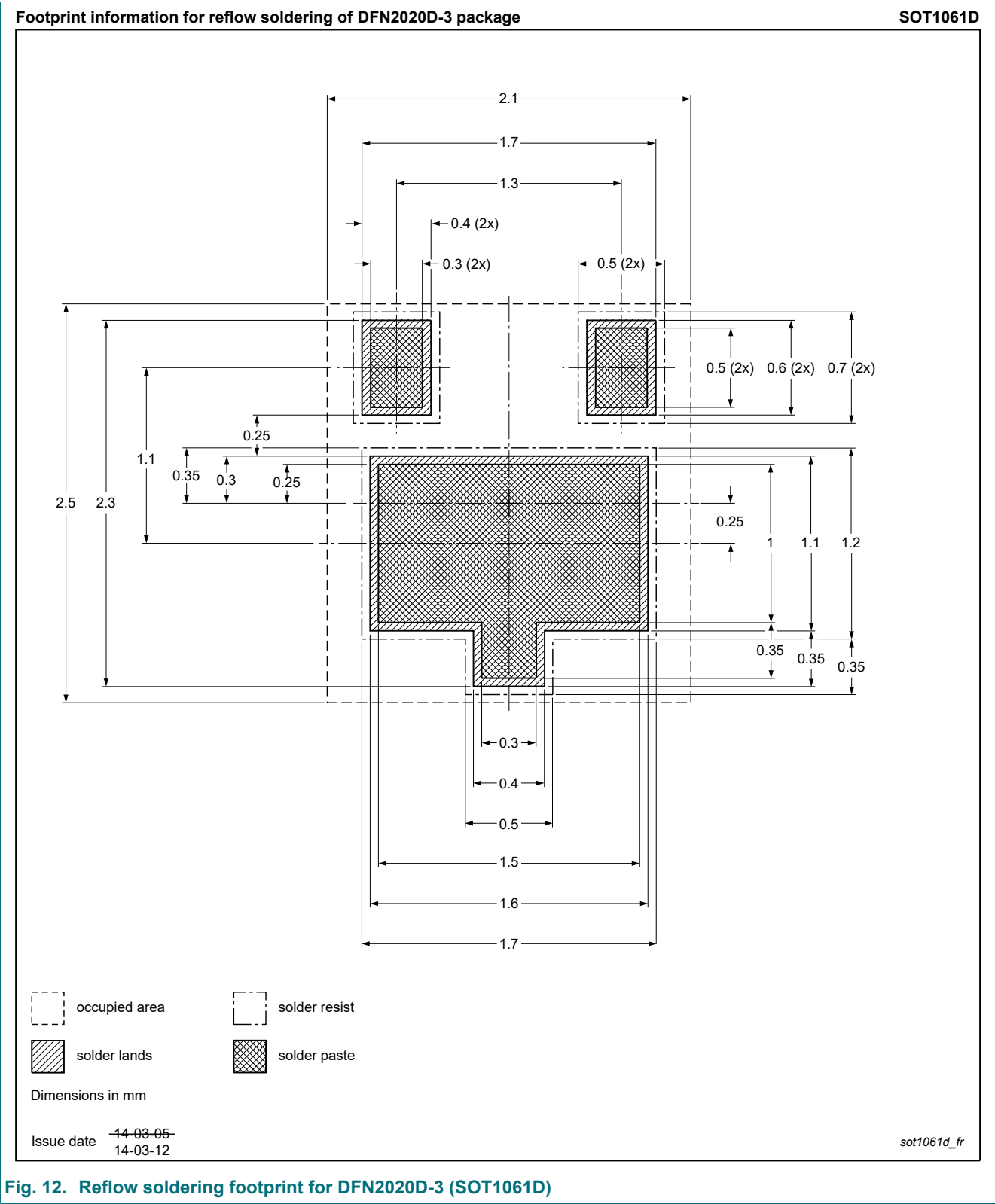


Fig. 12. Reflow soldering footprint for DFN2020D-3 (SOT1061D)



## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BC52XPAS-Q_SER v.1	20241024	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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